



# *C SUN*

志聖法人說明會

Investor Conference

**Morrison Liang, Chairman**

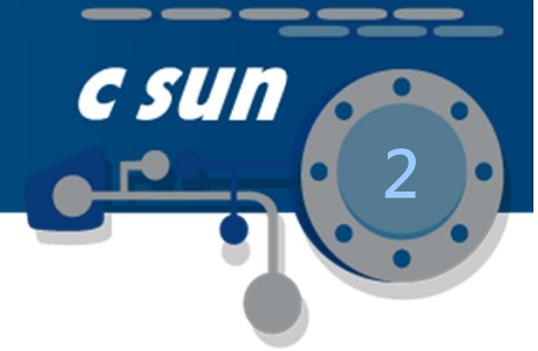
Dr. Toshio Huang, Executive Vice President of FPD Business Unit

Steven Lai, Executive Vice President of PCB Business Unit

Place: Taiwan Stock Exchange Corporation

October 30<sup>th</sup>, 2018

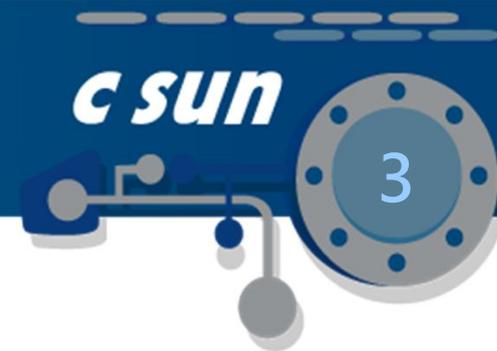
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# 兩岸四廠



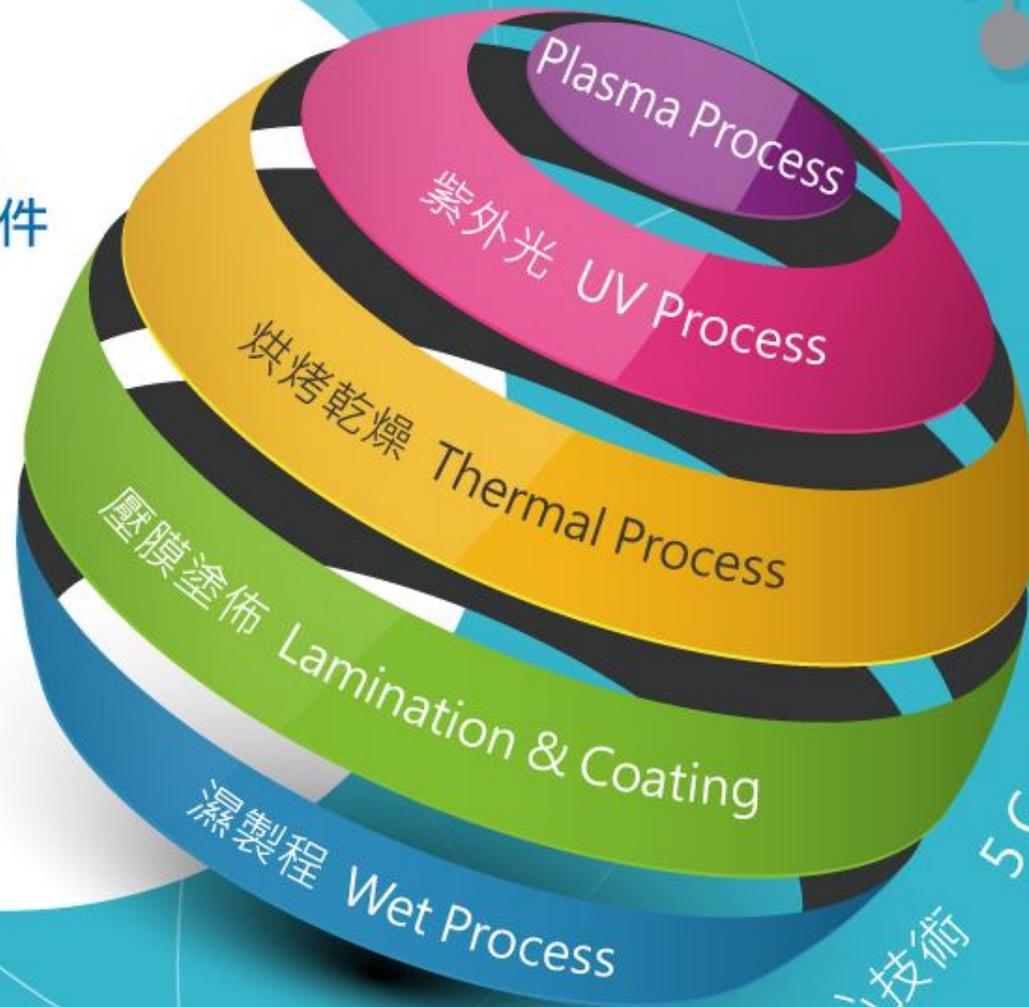
# 核心技術

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專利  
認證 **310** 件

發明  
件數 **69** 件



五大核心技術 5 Core Technologies

# 七個習慣

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他人之得，不必為自己之失  
大家都可以是贏家

**Think Win-Win**  
雙贏思維

了解彼此需求，  
做有效溝通的聆聽者  
**Seek First to Understand,  
then to be Understood**

知彼解己

尊重差異，整合不同觀點  
共創最佳的合作解決方法

**Synergize**  
統合綜效

不斷學習、持續進步  
身心平衡發展

**Sharpen the Saw**  
不斷更新

## The 7 Habits of Highly Effective People

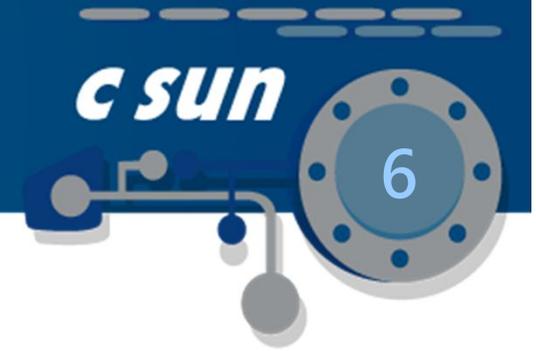
主動創造，  
打破障礙與限制

**Be Proactive**  
主動積極

確立目標  
克服困難徹底執行  
**Begin with the End  
in Mind 以終為始**

訂定優先順序，  
在關鍵任務與瑣碎事物中  
追求平衡

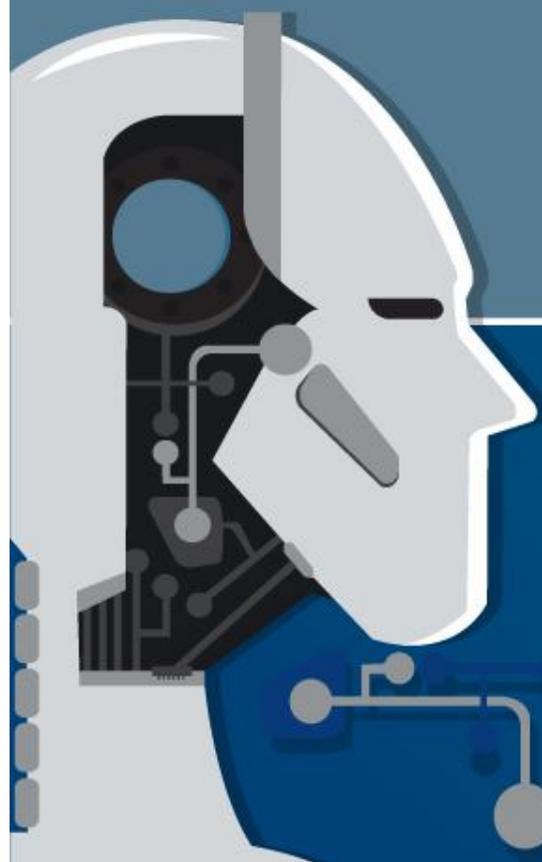
**First Things First**  
要事第一



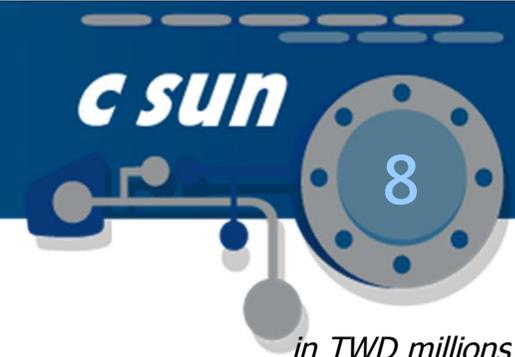
- 2018Q3 營運成果
  
- 市場機會與產品發展
  - Flat Panel Display (FPD)
  - Advanced Packaging(SEMI)
  - Printed Circuit Board(PCB)
  - 子公司 創峰
  
- Q&A

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2018 Q3 營運成果



# 2018Q3 營運成果



	2018Q3*		2017Q3		2017		2016		2015	
	Amount	%	Amount	%	Amount	%	Amount	%	Amount	%
Revenue-Consolidated	4,213		3,669		5,003		3,885		3,363	
COGS			2,414	65.8%	3,345	66.9%	2,722	70.1%	2,619	77.9%
Gross Margin			1,255	34.2%	1,658	33.1%	1,162	29.9%	744	22.1%
Operating Expense			825	22.5%	1,091	21.8%	951	24.5%	968	28.8%
Operating Income			430	11.7%	567	11.3%	212	5.5%	(224)	-6.7%
Net Non-Op. Profit			(45)	-1.2%	(53)	-1.1%	(10)	-0.3%	(419)	-12.4%
Net Income before tax			385	10.5%	514	10.3%	202	5.2%	(643)	-19.1%
Net Income after tax			320	8.7%	427	8.5%	200	5.1%	(730)	-21.7%
Attribute to stockholder's of the parent	399	9.5%	302	8.2%	403	8.1%	210	5.4%	(496)	-14.7%
ROE	17.09%		13.94%		18.20%		10.16%		-19.55%	
EPS (NT\$/after tax)	\$2.67		\$2.02		\$2.70		\$1.39		(\$3.12)	
Debt Ratio			61.36%		59.81%		62.17%		62.69%	

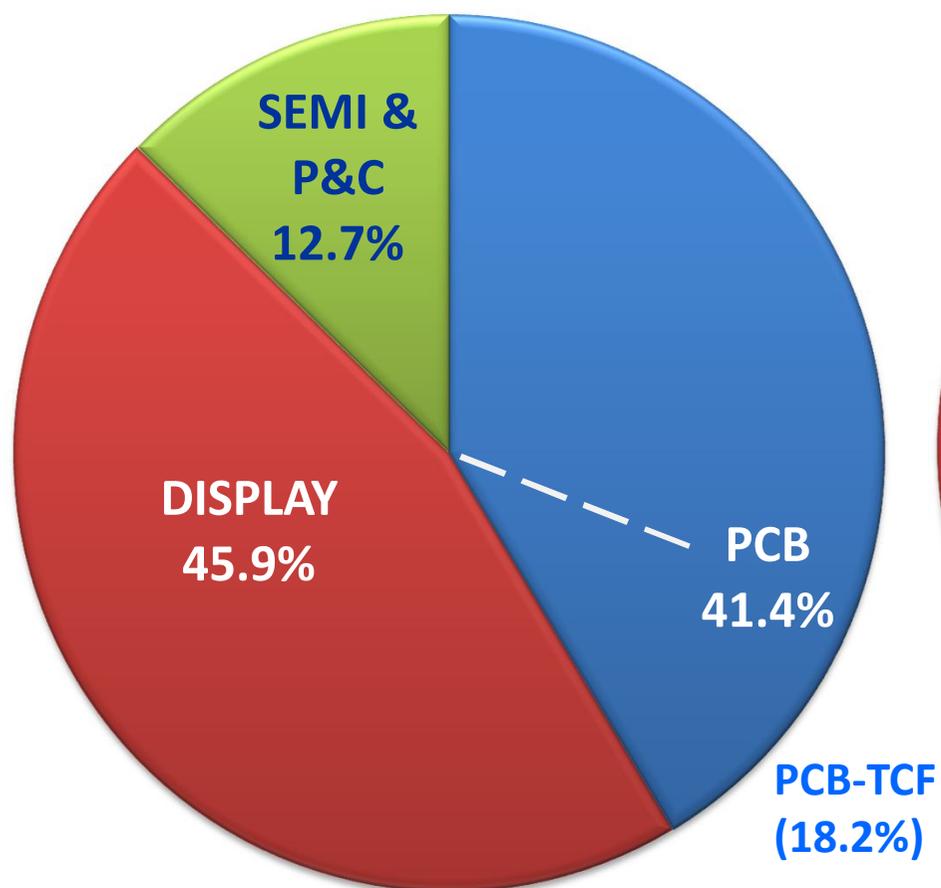
Note : \* unaudited

# 產業別營業收入

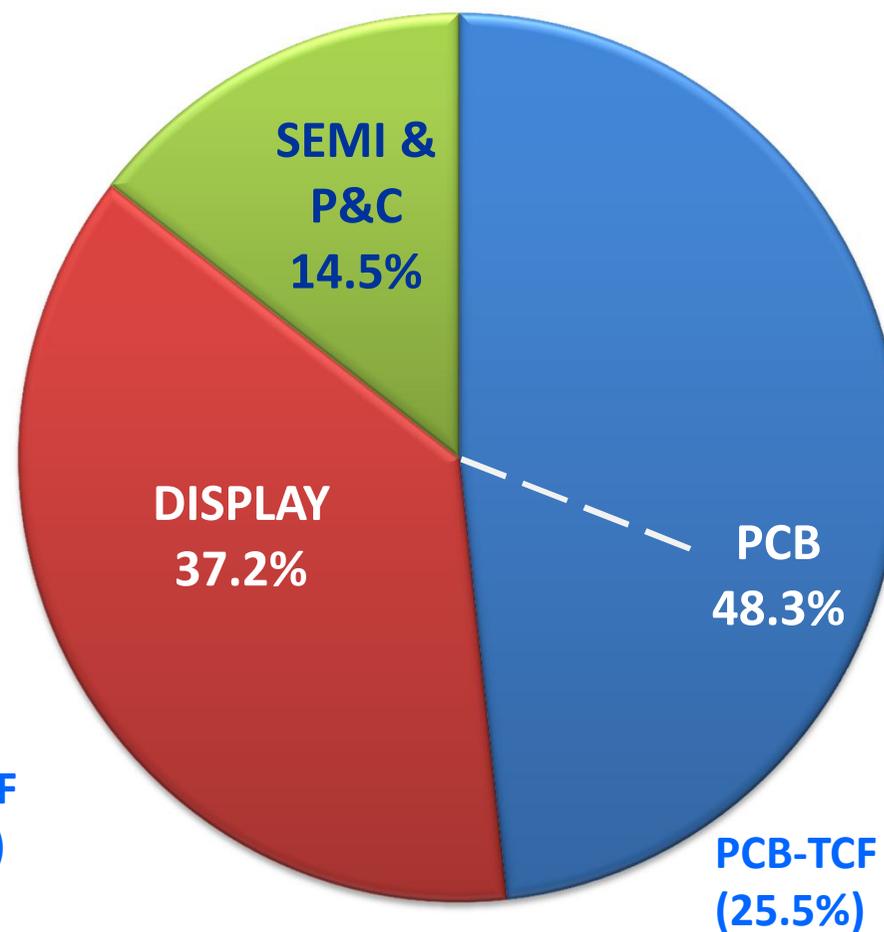
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## 2017

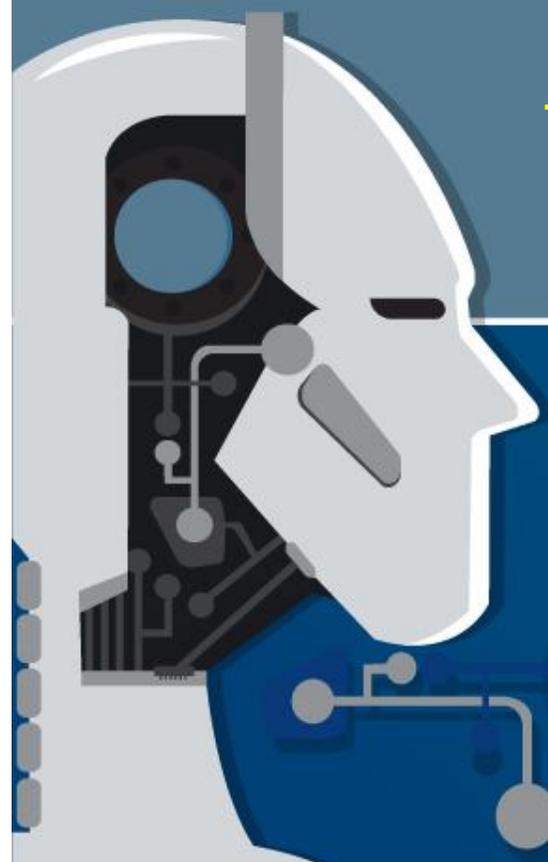


## 2018/1~9



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市場機會與產品發展



# SEMI/FPD之光、熱核心技術

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真空/自動化  
OVEN(SEMI)



熱風 for TFT



UV2 for TFT



熱板 for TFT

**FPD BU**

# G8.6 & G11 設備市佔率擴大

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- G8.6/G11設備擴產多，現有客戶與未來擴廠

*SDP*

超视界国际科技（广州）有限公司

*CEC*  
中国电子

*CHOT*



**HKC**



**FPD BU**

# 車載面板-網印後自動化乾燥生產線

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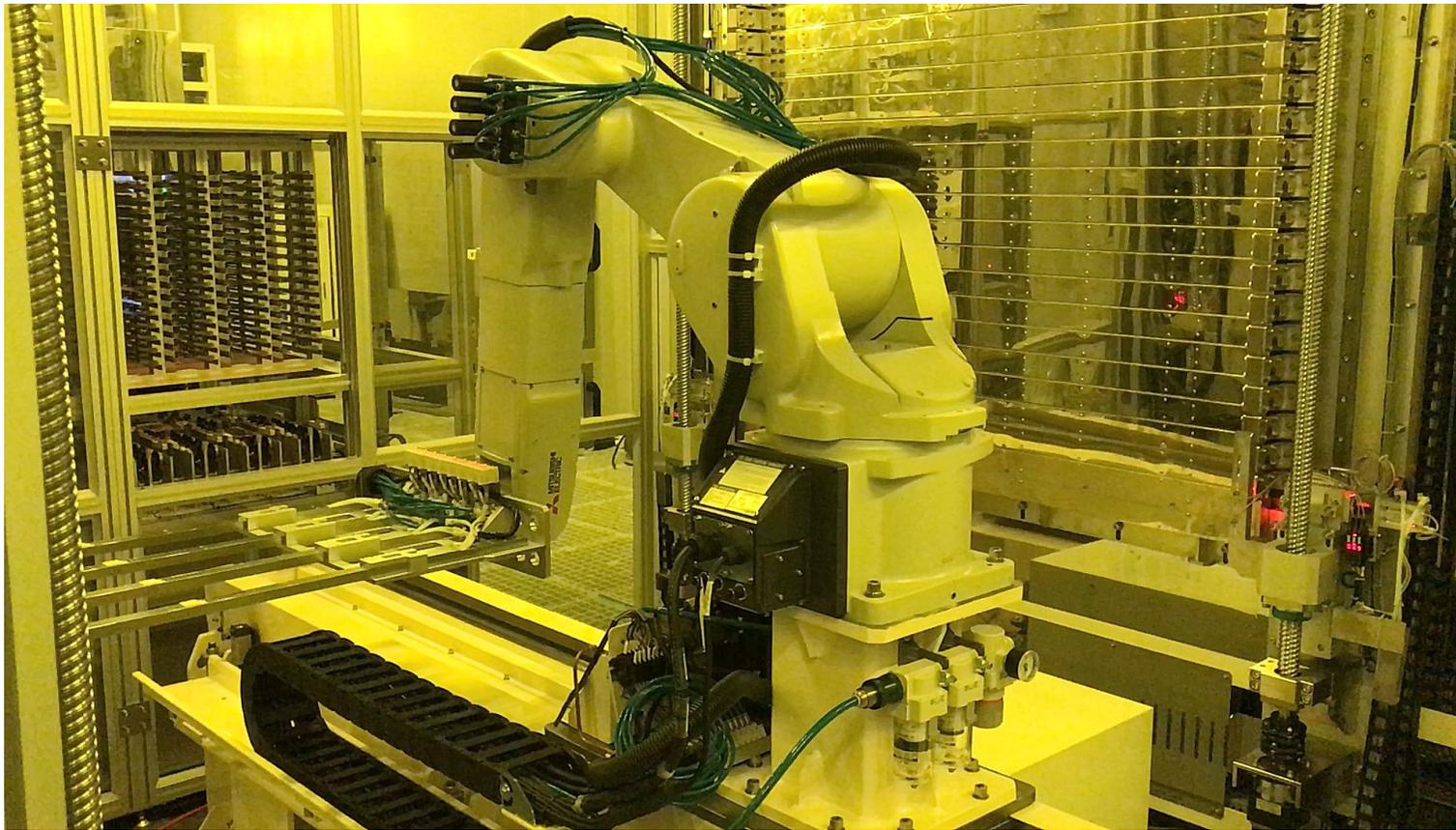
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- 車載顯示面板，網印後自動化乾燥生產線，開發完成導入量產線。



**FPD BU**

- 3D玻璃機殼防破碎製程已導入志聖生產設備

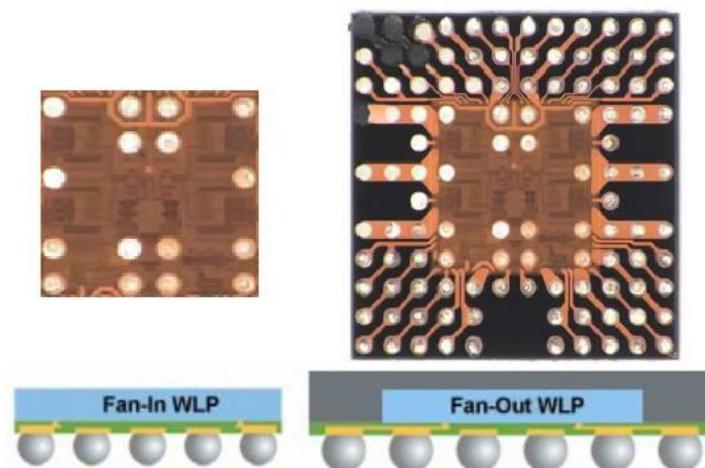


# 半導體先進封裝製程持續發展

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- 先進封裝製程發展快速(Fan-Out)，封裝載具變化(WLP、PLP)。
- 熱技術應用與現況：
  - 先進封裝Molding段:與外商合作切入Molding 固化製程。
  - 與客戶合作開發切入PLP RDL 全自動烘烤設備，製程驗證中
  - 傳統Oven結合自動化技術，導入客戶端
- 中國開始發展先進封裝製程，設備需求啟動

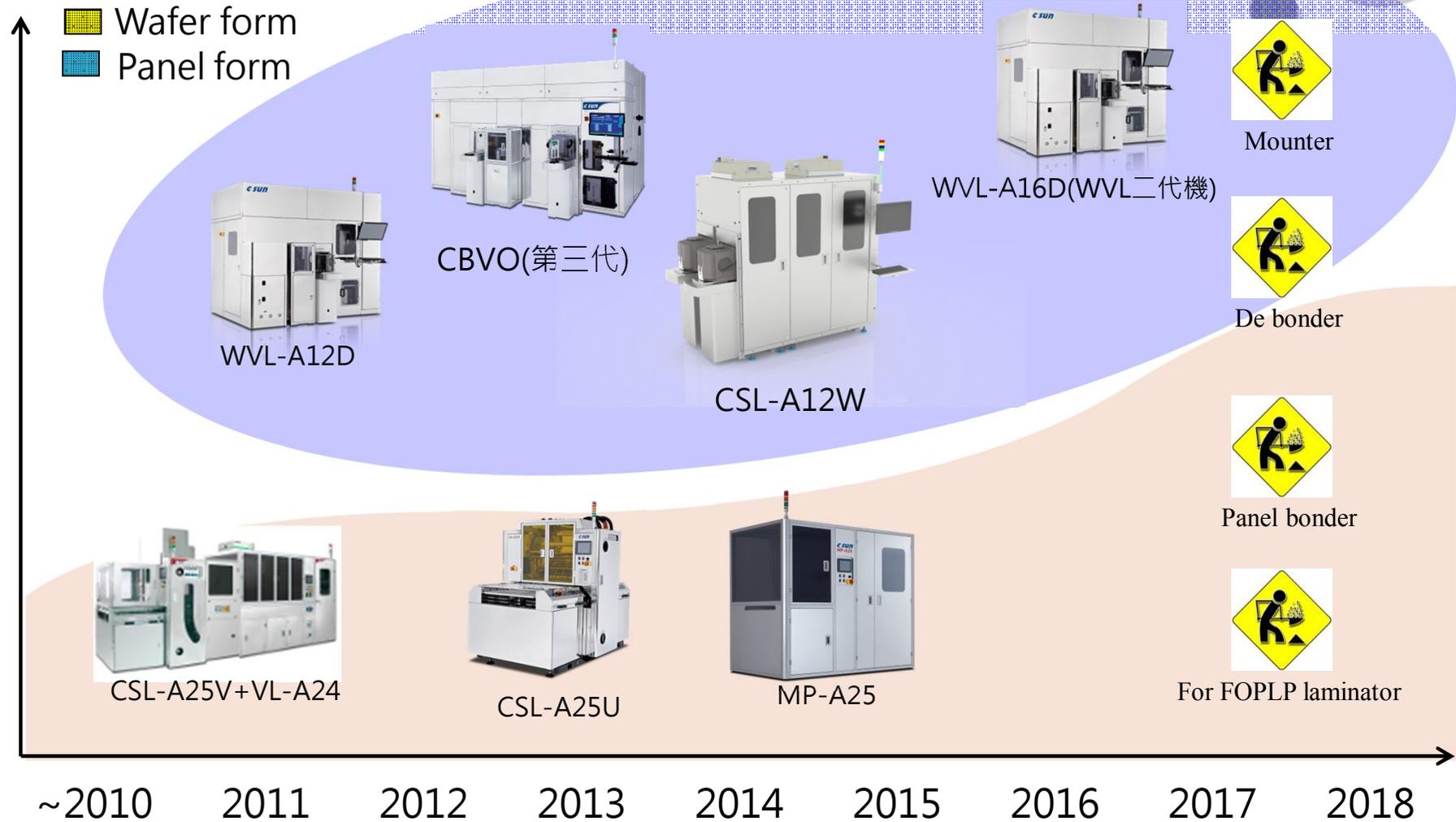


**FPD BU**

# 半導體設備發展規劃

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PCB BU

# SEMI設備緊跟先進封裝製程

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- 高階AI先進封裝製程
- 消費性晶片先進封裝製程



**PCB BU**

# 壓膜、曝光、智能生產的核心技術

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應用於：PCB、半導體、太陽能



**PCB BU**

# 曝光技術沿革與展望

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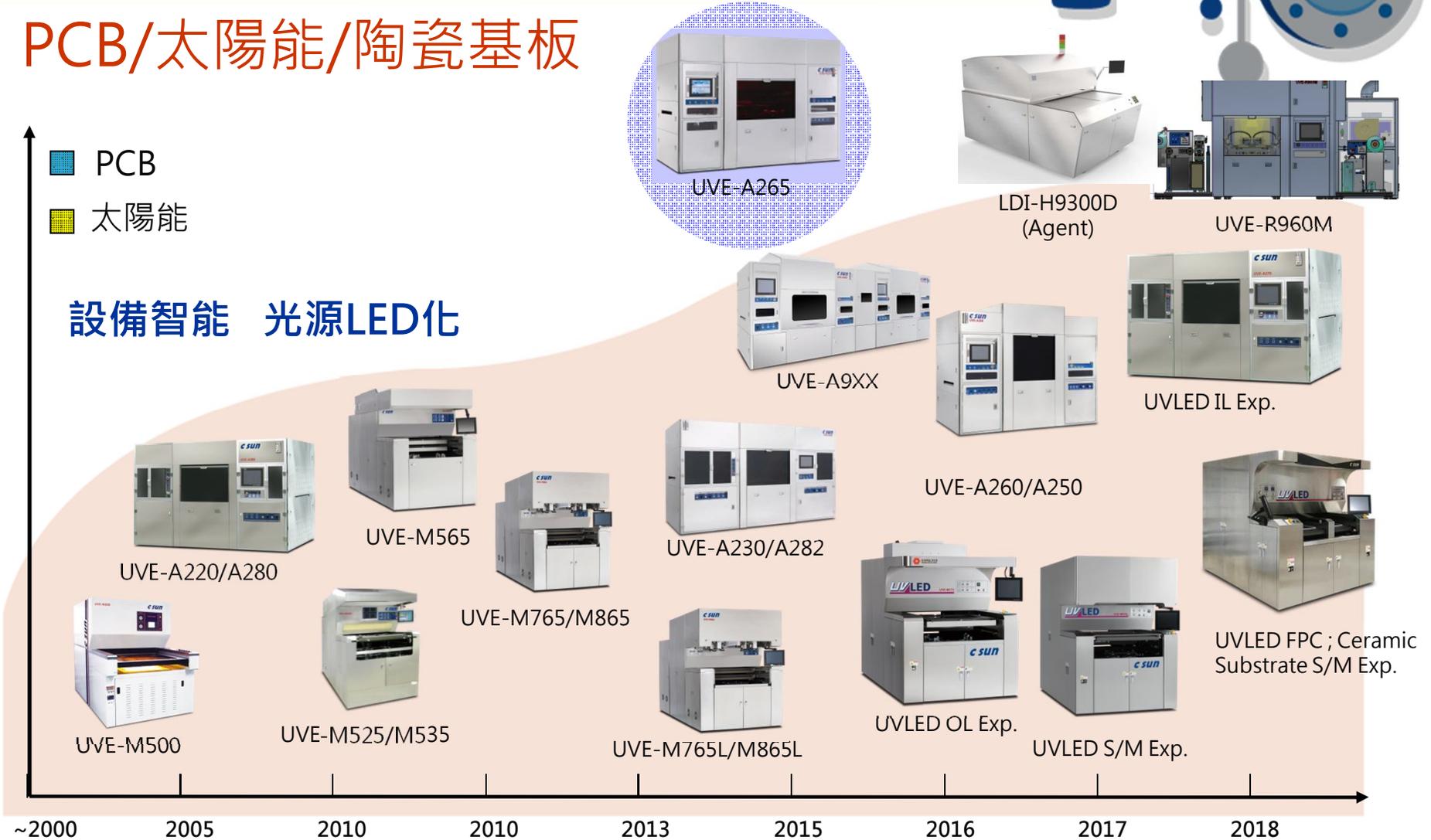
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## PCB/太陽能/陶瓷基板

■ PCB

■ 太陽能

設備智能 光源LED化



# PCB BU

# 壓膜技術沿革與展望

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## PCB/太陽能/陶瓷基板

■ PCB

■ 太陽能

設備智能 跨產業應用



RC-A24



CSL-A25V+VL-A24



MP-A25



PL-A24



CSL-A25



CSL-A32



CSL-A25PH II



CSL-A25U II



RTR-500PH

~1996

2000

2004

2009

2010

2014

2016

2017

2018

PCB BU

# 智能化服務應用情境說明

現在(As-Is)

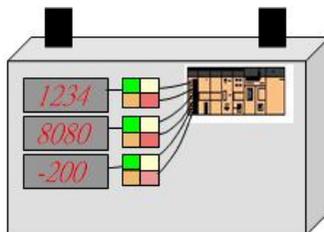
未來(To-Be)

設備這麼多，人力永遠不夠

智能化預測維護與監控

透過定期檢點管理表定期檢驗，零件異常而停機時，進行替換零件。

機台狀態數值異常，不知道哪個元件出錯。

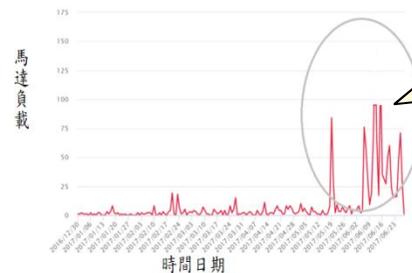


機台狀態顯示畫面

底片對位設定(μm)	
對位移動量	3
底片精度	50
初對位設定(μm)	
對位移動量	10
真空檢測設定(μm)	
對位移動量	999
D精度	999
底片精度	999

有時候操作員為了提高產能擅自修改機台設定值，又產生好多報廢。

曝光源光源均勻度量測：  
1天3班，每個班都要量1次30分鐘，好浪費時間，有時數據隨便寫，反正主管也不知道。

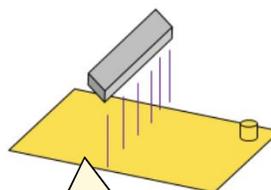


實時監測馬達負載，即將發生異常，即時通知工務趁待料時檢修，僅停機4小時且不影響產能。

區域B感測器3號Cable發生斷線，請確認連接器配線。



通訊



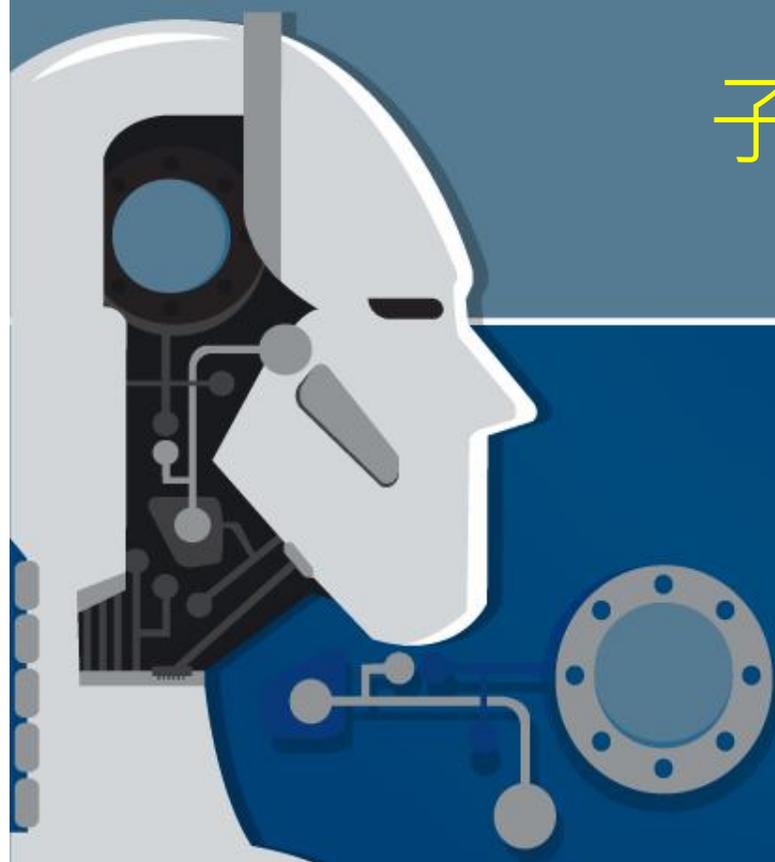
智慧型自動偵測光源功能，一鍵執行，數據自動上傳，確保製程穩定，也不用在人工抄寫數據。



料號重要參數統一由上位系統下達，有效避免報廢。

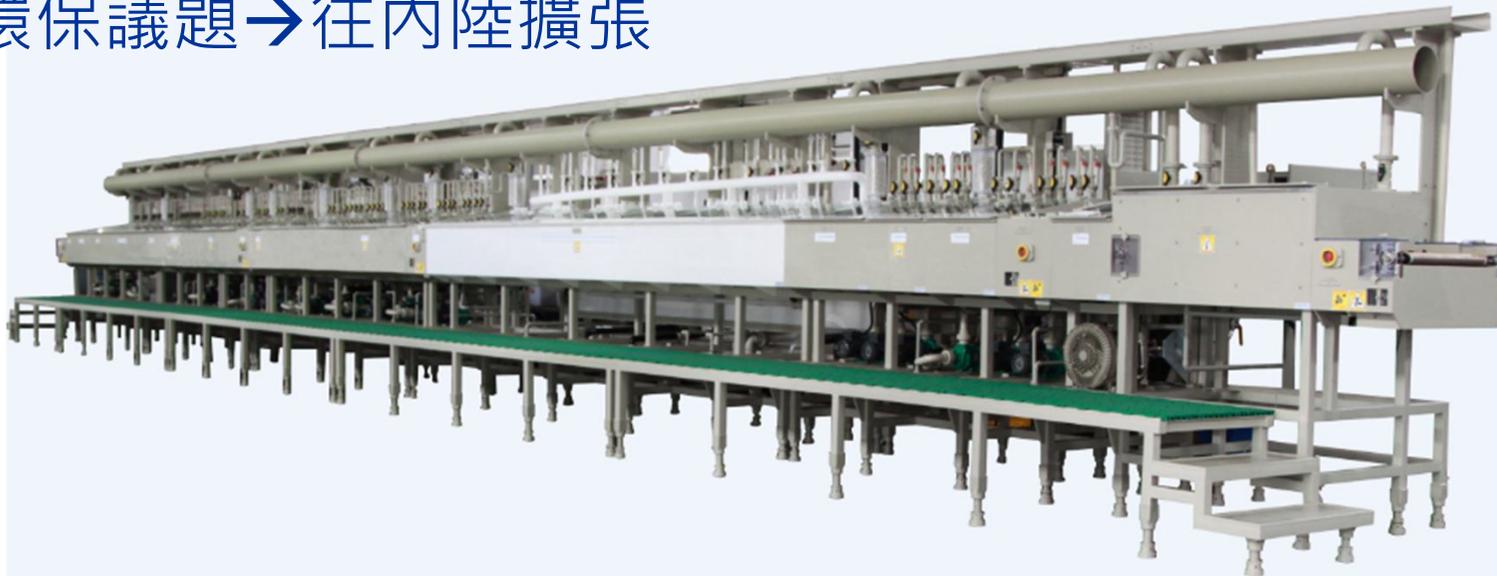
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子公司-創峰



## 2018營收成長動能

- Desmear PTH取代既有龍門線設備
  - 耗能、耗水、耗藥水
  - 汰舊換“節能、環保”設備
- 沿海環保議題 → 往內陸擴張





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Thank You